Abstracts

Low cost multi-layer ceramic package for flip-chip MMIC up to W-band

M. Ito, K. Maruhashi, K. Ikuina, N. Senba, N. Takahashi and K. Ohata. "Low cost multi-layer ceramic package for flip-chip MMIC up to W-band." 2000 MTT-S International Microwave Symposium Digest 00.1 (2000 Vol. I [MWSYM]): 57-60.

We have developed a low cost multi-layer low temperature co-fired ceramic (LTCC) package based on a mass production design rule for an MMIC up to W-band. The package structure includes a cavity for the flip-chip MMIC and coplanar feed-throughs improved to suppress radiation. Good small-signal characteristics of a 76 GHz-band amplifier mounted on the package are demonstrated.

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